In the Claims:

Please amend claims 1, 5, 10, 19 and 20 as follows:

1. (Currently Amended) A composition for removing residues from the microstructure of an object comprising:

carbon dioxide;

an additive for removing the residues comprising a fluoride having a formula $NR_1R_2R_3R_4F$, where R_1 , R_2 , R_3 , and R_4 are each independently a hydrogen or an alkyl group; and

a co-solvent for dissolving said additive in said CO₂ at a pressurized fluid condition.

- 2. (Original) The composition of claim 1 wherein the additive further comprises a basic compound.
- 3 4. (Canceled).
- (Currently Amended) A composition for removing residues from the microstructure of an object comprising:

carbon dioxide,

- a compound having a hydroxyl group,
- a fluoride having a formula $NR_1R_2R_3R_4F$, where R_1 , R_2 , R_3 , and R_4 are each independently a hydrogen or an alkyl group.
- 6. (Original) The composition of claim 5 further comprising a basic compound.
- 7. (Original) The composition of claim 6 wherein the basic compound is selected from a quatenaryammoniumhydroxide, an alkylamine, an alkanolamine, a hydroxylamine, and mixtures thereof.
- 8. (Original) The composition of claim 5 further comprising a co-solvent selected from dimethylacetamide, propylene glycol, dimethylsulfoxide, deionized water, acetic acid, and mixtures thereof.

- (Original) The composition of claim 8 wherein the co-solvent comprises deionized water.
- 10. (Currently Amended) The composition of claim 8 wherein the co-solvent is substantially free of does not include water.

11 - 12. (Canceled).

- 13. (Original) The composition of claim 5 wherein the fluoride is selected from ammonium fluoride, tetramethylammoniumfluoride, tetraethylammoniumfluoride, tetrabutylammoniumfluoride, tetrapropylammoniumfluoride, choline fluoride, and mixtures thereof.
- 14. (Original) The composition of claim 5 wherein the compound is selected from ethanol, methanol, n-propanol, isopropanol, n-butanol, iso-butanol, diethyleneglycolmonomethylether, diethyleneglycolmonoethylether, hexafluoro-isopropanol, and mixtures thereof.
- 15. (Canceled)
- 16. (Currently Amended) The composition of claim 19 wherein the additive is dissolved within the eosolvent co-solvent.
- 17. (Canceled)
- 18. (Previously Presented) The composition of claim 19 wherein the residues are at least one selected from photoresist, UV-hardened resist, X-ray hardened resist, ashed resists, carbon-fluorine containing polymer, plasma etch residues, organic process contaminants, and inorganic process contaminants.
- 19. (Currently Amended) A composition for removing residues from the microstructure of an object comprising:

carbon dioxide wherein the carbon dioxide is in a pressurized or a supercritical fluid state;

an additive comprising a fluoride having a formula $NR_1R_2R_3R_4F$, where R_1 , R_2 , R_3 , and R_4 are each independently a hydrogen or an alkyl group, and mixtures thereof and optionally a basic compound; and

a cosolvent co-solvent selected from an alcohol, dimethylacetamide, propylene glycol, dimethylsulfoxide, deionized water, acetic acid, acetone, ethanol, propanol, dimethylformamide, N-methyl-2-pyrrodine N-methyl-2-pyrrolidone, diethylene glycol methyl ether, and mixtures thereof.

20. (Currently Amended) A composition for removing residues from the microstructure of an object comprising:

from 0.001 to 8 weight percent of an additive comprising a fluoride having a formula $NR_1R_2R_3R_4F$, where R_1 , R_2 , R_3 , and R_4 are each independently a hydrogen or an alkyl group, and mixtures thereof and optionally a basic compound;

from 1 to 50 weight percent of a eosolvent co-solvent selected from an alcohol, dimethylacetamide, propylene glycol, dimethylsulfoxide, deionized water, acetic acid, acetone, ethanol, propanol, dimethylformamide, N-methyl 2-pyrrodine N-methyl-2-pyrrolidone, diethylene glycol methyl ether, and mixtures thereof; and

carbon dioxide.

- 21. (Previously Presented) The composition of claim 20 wherein the additive further comprises methane.
- 22. (Previously Presented) The composition of claim 20 wherein the additive further comprises a surfactant having a CFx group.

Please add new claim 23 as follows:

23. (New) A composition for removing residues from the microstructure of an object comprising:

carbon dioxide;

an additive for removing the residues comprising a fluoride having a formula $NR_1R_2R_3R_4F$, where R_1 , R_2 , R_3 , and R_4 are each independently a hydrogen or an alkyl group, and a quaternary ammonium hydroxide; and

a co-solvent for dissolving said additive in said CO_2 at a pressurized fluid condition.